

F

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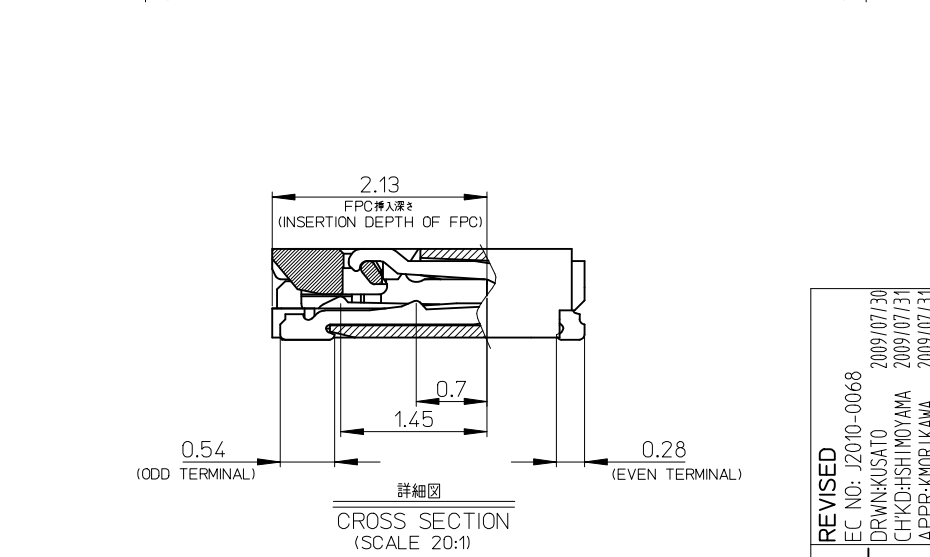
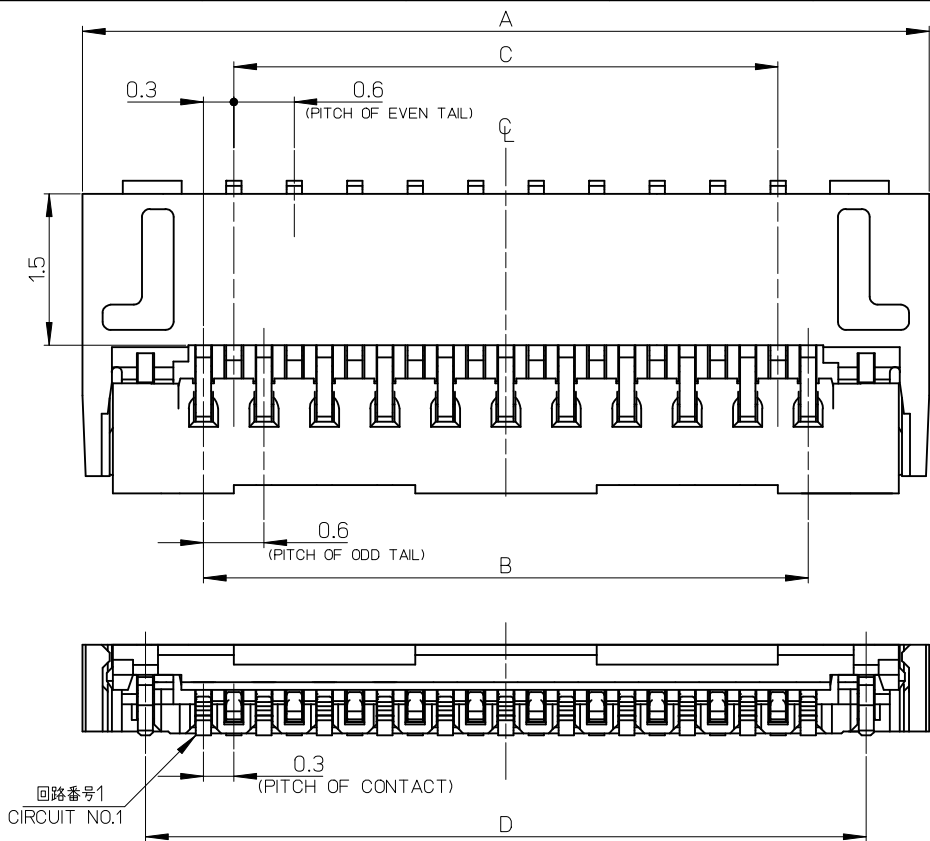
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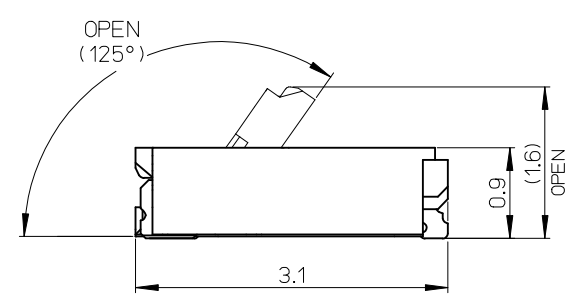
C

B

A



注記
NOTES:
1.材質
MATERIAL
ハウジング:LCP(液晶ポリマー)、ガラス充填、UL94V-0
HOUSING:LCP(LIQUID CRYSTAL POLYMER),
GLASS FILLED,UL94V-0
アクチュエータ:ナイロン、ガラス充填、UL94V-0
ACTUATOR:NYLON(POLYAMIDE),
GLASS FILLED,UL94V-0
ターミナル:銅合金(t=0.15)
TERMINAL:COPPER ALLOY(t=0.15)
金具:銅合金(t=0.15)
NAIL:COPPER ALLOY(t=0.15)
2.めっき仕様
PLATING
ターミナル
TERMINAL
部分金めっき
SEPARATED GOLD PLATING
下地ニッケルめっき
UNDER PLATING:NICKEL PLATING
金具
NAIL
銅めっき
TIN PLATING
下地ニッケルめっき
UNDER PLATING:NICKEL PLATING
3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.
4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



0.10	16.15	14.4	15	17.4	501628-5191	51
0.089	14.35	12.6	13.2	15.6	501628-4591	45
0.078	12.55	10.8	11.4	13.8	501628-3991	39
0.075	11.95	10.2	10.8	13.2	501628-3791	37
0.071	11.35	9.6	10.2	12.6	501628-3591	35
0.067	10.75	9.0	9.6	12.0	501628-3391	33
0.064	10.15	8.4	9	11.4	501628-3191	31
0.056	8.95	7.2	7.8	10.2	501628-2791	27
0.046	7.15	5.4	6	8.4	501628-2191	21
0.028	4.15	2.4	3	5.4	501628-1191	11
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER No.	極数 CIRCUITS

REVISED
EC NO: J2010-0068
2009/07/30
DRINKUSATO
2009/07/31
CHKD:SHIMOMYAMA
2009/07/31
APPR:KMORI KAWA
2009/07/31

DESCRIPTION
10 UNDER ±0.2
10 OVER 30 UNDER ±0.25
30 OVER ±0.3
ANGULAR ±1 °
DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

REV

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER ±0.2
10 OVER 30 UNDER ±0.25
30 OVER ±0.3
ANGULAR ±1 °
DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY
HSHIMOMYAMA
2005/03/25
CHECKED BY
HHIRATA
2005/03/25
APPROVED BY
MSASAO
2005/03/25
MATERIAL NO.
SEE TABLE
SIZE
A3

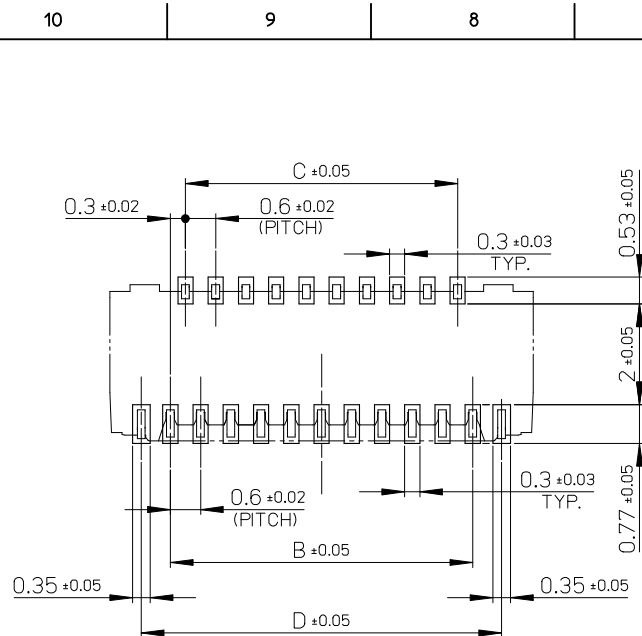
SCALE
40:1

DESIGN UNITS
METRIC

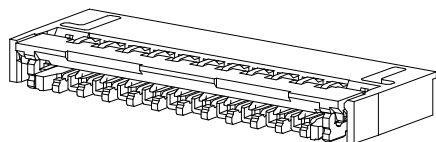
THIRD ANGLE
PROJECTION

0.3 FPC CONN. (H=0.9)
HS'G ASSY BOTTOM CONTACT
NICKEL BARRIER
MOLEX INCORPORATED
DOCUMENT NO.
SD-501628-001
SHEET NO.
1 OF 2

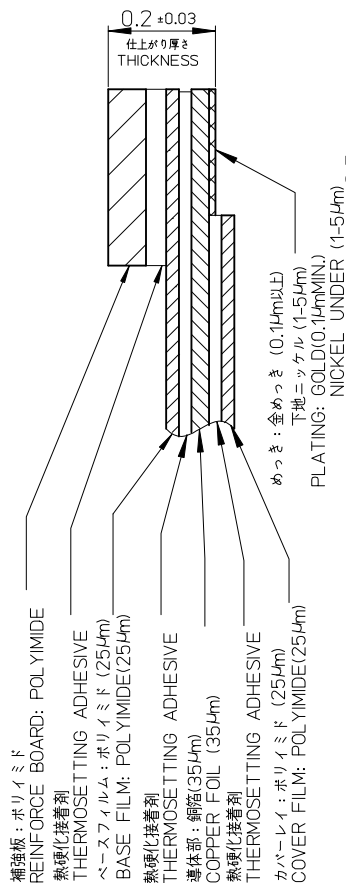
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



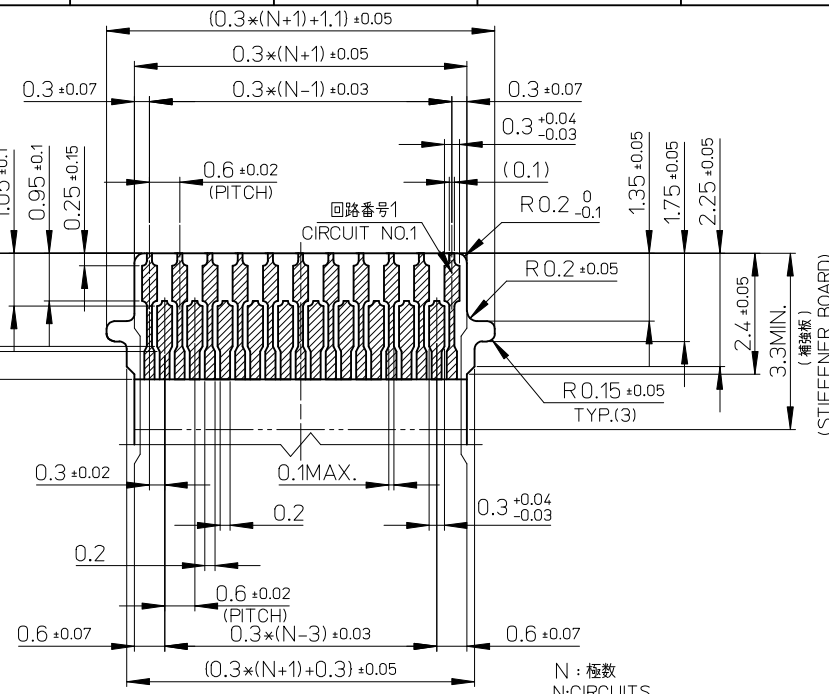
推奨基板寸法
RECOMMENDED P.C.B. PATTERN LAYOUT
(SCALE 5:1)



ISO VIEW (参考)



FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ASHESIVE ON THE
CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE
THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO.: J2010-0068 DRAWN:KUSATO CHKD:HSIMOYAMA APPR:KMORIKAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 40:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY HSIMOYAMA	DATE 2005/03/25	TITLE 0.3 FPC CONN. (H=0.9) HS'G ASSY BOTTOM CONTACT NICKEL BARRIER				
		10 OVER 30 UNDER	± 0.25	CHECKED BY HHIRATA	DATE 2005/03/25					
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2005/03/25					
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501628-001		2 OF 2		
		REV		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10

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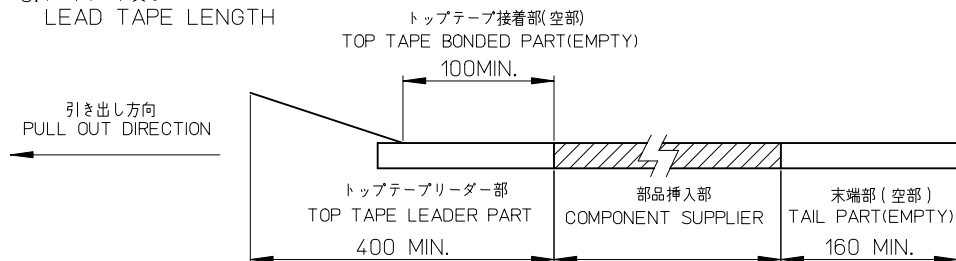
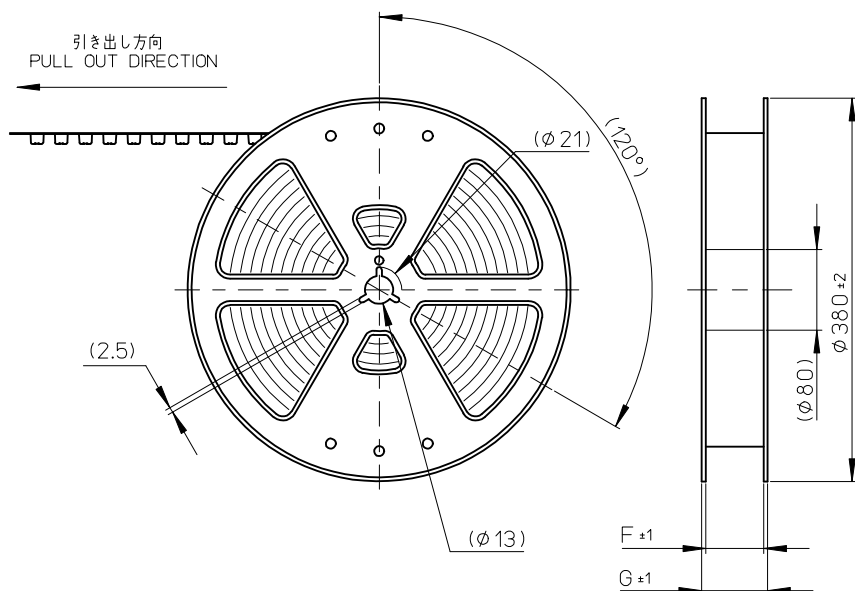
3

2

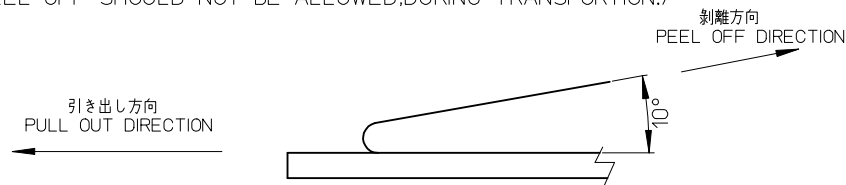
1

注記)
NOTES

- 製品番号501628-**11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 501628-**11 DETAIL DIMENSIONS,
SEE SALES DRAWING FOR CONNECTOR.
- 梱包数量: 3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度 (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
0.1-1.3N (10-130gf)
尚、本規格値は出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しないこと)
(PEEL OFF SHOULD NOT BE ALLOWED,DURING TRANSPORTION.)



- 材料
MATERIAL
キャリアテープ: ポリスチレン (PS)
CARRIER TAPE: POLYSTYRENE (PS)
トップテープ: PET、PE、PEF
TOP TAPE : PET、PE、PEF
リール: ポリスチレン
REEL: POLYSTYLENE

- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

REVISED EC NO: J2010-0068 DRAWN:KUSATO 2009/07/30 CHKD:HSHIMOYAMA 2009/07/31 APPR:KMORI KAWA 2009/07/31	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY HSHIMOYAMA	DATE 2005/08/22	TITLE 0.3 FPC CONN.(FOR 501628 -**11) TAPING PACKAGE NICKEL BARRIER				
		10 OVER 30 UNDER	± ---	CHECKED BY HIRATA	DATE 2005/08/22					
		30 OVER	± ---	APPROVED BY MSASAO	DATE 2005/08/22					
		ANGULAR ± --- °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-501628-003		SHEET NO. 1 OF 2		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
	REV									

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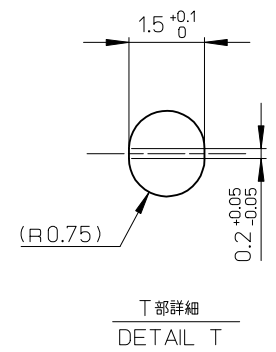
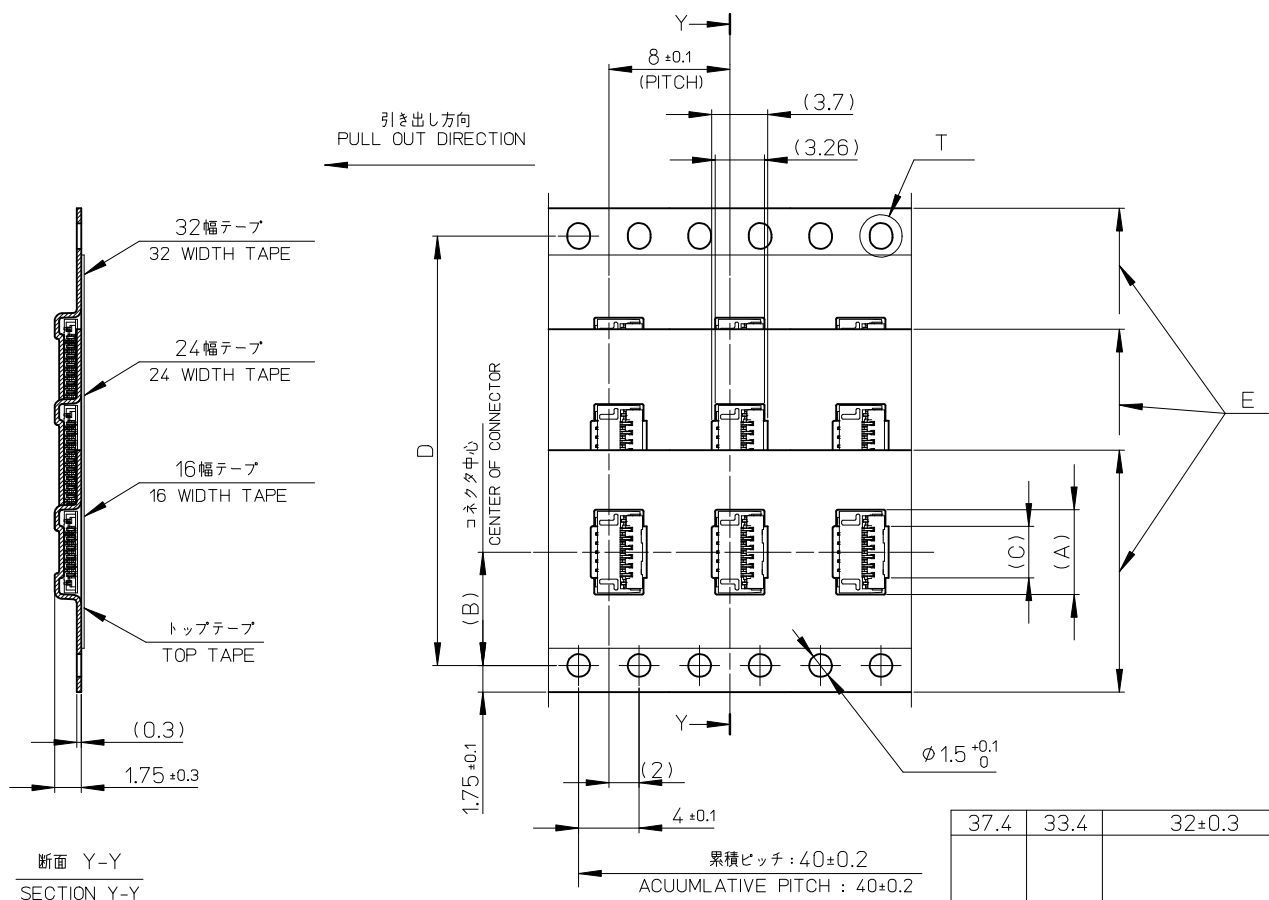
E

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断面 Y-Y
SECTION Y-Y

37.4	33.4	32±0.3	28.4	15.4	14.2	17.6	501628-5191	51
29.4	25.4	24±0.3	++	13.6	11.5	15.8	501628-4591	45
				11.8		14	501628-3991	39
				11.2		13.4	501628-3791	37
				10.6		12.8	501628-3591	35
				10.0		12.2	501628-3391	33
				9.4		11.6	501628-3191	31
21.4	17.4	16±0.3	8.2	7.5	10.4	501628-2791	27	
			6.4		8.6	501628-2191	21	
			3.4		5.6	501628-1191	11	
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	製 品 番 号 MATERIAL NO.	極 数 CIRCUITS

REVISED EC NO: J2010-0068 DRWN: KUSATO CHKD: HSHIMOMYAMA APPR: KMORIKAWA G	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		10 UNDER	± ---	DRAWN BY HSHIMOMYAMA	DATE 2005/08/22	TITLE 0.3 FPC CONN.(FOR 501628 -**11) TAPING PACKAGE NICKEL BARRIER MOLEX INCORPORATED					
		10 OVER 30 UNDER	± ---	CHECKED BY HIRATA	DATE 2005/08/22						
		30 OVER	± ---	APPROVED BY MSASAO	DATE 2005/08/22						
		ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501628-003		2 OF 2			
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									